

AF/2815

PATENT

Docket No.: 50090-234



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application of

: Response Under 37 CFR 1.116 - Expedited Procedure

Kozo HARADA, et al.

Serial No.: 09/635,902

: Group Art Unit: 2815

Filed: August 11, 2000

: Examiner: Chris, Chu

Corres. and Mail
BOX AF

For: SEMICONDUCTOR DEVICE HAVING DENSELY STACKED SEMICONDUCTOR CHIPS

Box AF
THE COMMISSIONER FOR PATENTS AND TRADEMARKS
Washington, DC 20231

Dear Sir:

Transmitted herewith is an Amendment in the above identified application.

- ☒ No additional fee is required.
- ☐ Applicant is entitled to small entity status under 37 CFR 1.27
- ☐ Also attached:

The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	10	20	0	\$18.00 =	\$0.00
Independent Claims	2	4	0	\$84.00 =	\$0.00
Multiple claims newly presented					\$0.00
Fee for extension of time					\$0.00
					\$0.00
Total of Above Calculations					\$0.00

- ☐ Please charge my Deposit Account No. 500417 in the amount of \$0.00. An additional copy of this transmittal sheet is submitted herewith.
- ☒ The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. 500417, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

McDERMOTT, WILL & EMERY

for *Becker* #46,692
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

: **RESPONSE UNDER 37 CFR 1.116**

Kozo HARADA, et al.

: **EXPEDITED PROCEDURE**

Serial No.: 09/635,902

: Group Art Unit: 2815

Filed: August 11, 2000

: Examiner: Chris Chu

For: SEMICONDUCTOR DEVICE HAVING DENSELY STACKED SEMICONDUCTOR
CHIPS

SUPPLEMENTAL AMENDMENT UNDER 37 CFR 1.116

Box AF

Commissioner for Patents

Washington, DC 20231

Sir:

In furtherance to the complete response filed June 3, 2002, which was fully responsive to the final Office Action dated March 1, 2002, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend claim 14 to read as follows:

14. A semiconductor device comprising:

a plurality of semiconductor chips each having electrodes formed on the major surface thereof, and

a plurality of spacer members each having a conductive pattern on the surface thereof;

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